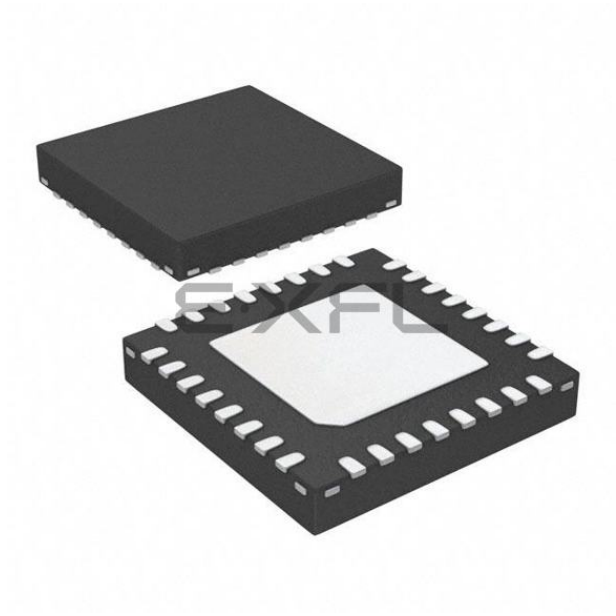

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	32-HVQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc11e14fhn33-401

- Digital peripherals:
  - Up to 54 General-Purpose I/O (GPIO) pins with configurable pull-up/pull-down resistors, repeater mode, and open-drain mode.
  - Up to 8 GPIO pins can be selected as edge and level sensitive interrupt sources.
  - Two GPIO grouped interrupt modules enable an interrupt based on a programmable pattern of input states of a group of GPIO pins.
  - High-current source output driver (20 mA) on one pin.
  - High-current sink driver (20 mA) on true open-drain pins.
  - Four general-purpose counter/timers with a total of up to 8 capture inputs and 13 match outputs.
  - Programmable Windowed WatchDog Timer (WWDT) with a dedicated, internal low-power WatchDog Oscillator (WDO).
- Analog peripherals:
  - 10-bit ADC with input multiplexing among eight pins.
- Serial interfaces:
  - USART with fractional baud rate generation, internal FIFO, a full modem control handshake interface, and support for RS-485/9-bit mode and synchronous mode. USART supports an asynchronous smart card interface (ISO 7816-3).
  - Two SSP controllers with FIFO and multi-protocol capabilities.
  - I^2C-bus interface supporting the full I^2C-bus specification and Fast-mode Plus with a data rate of up to 1 Mbit/s with multiple address recognition and monitor mode.
- Clock generation:
  - Crystal Oscillator with an operating range of 1 MHz to 25 MHz (system oscillator).
  - 12 MHz high-frequency Internal RC oscillator (IRC) that can optionally be used as a system clock.
  - Internal low-power, low-frequency WatchDog Oscillator (WDO) with programmable frequency output.
  - PLL allows CPU operation up to the maximum CPU rate with the system oscillator or the IRC as clock sources.
  - Clock output function with divider that can reflect the crystal oscillator, the main clock, the IRC, or the watchdog oscillator.
- Power control:
  - Integrated PMU (Power Management Unit) to minimize power consumption during Sleep, Deep-sleep, Power-down, and Deep power-down modes.
  - Power profiles residing in boot ROM allow optimized performance and minimized power consumption for any given application through one simple function call.
  - Four reduced power modes: Sleep, Deep-sleep, Power-down, and Deep power-down.
  - Processor wake-up from Deep-sleep and Power-down modes via reset, selectable GPIO pins, or a watchdog interrupt.
  - Processor wake-up from Deep power-down mode using one special function pin.
  - Power-On Reset (POR).
  - Brownout detect with four separate thresholds for interrupt and forced reset.

6. Pinning information

6.1 Pinning

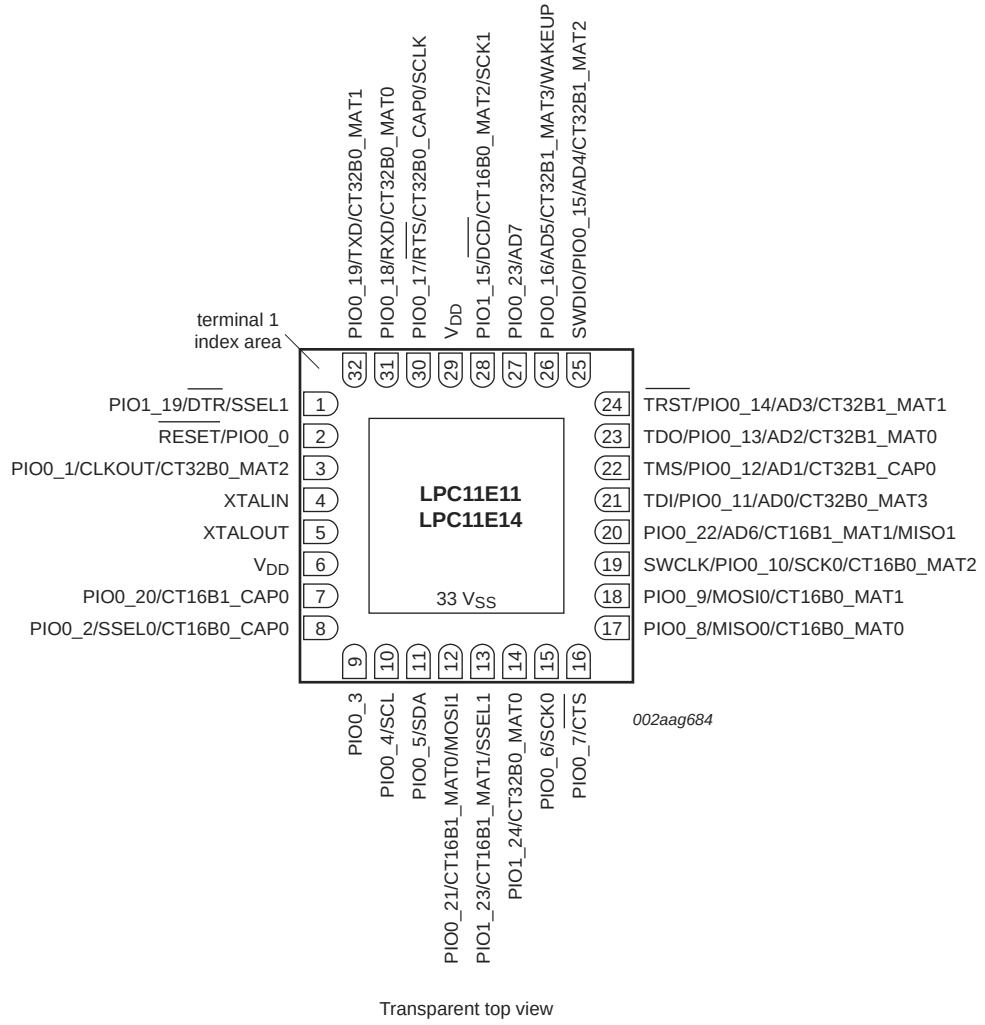


Fig 2. Pin configuration (HVQFN33)

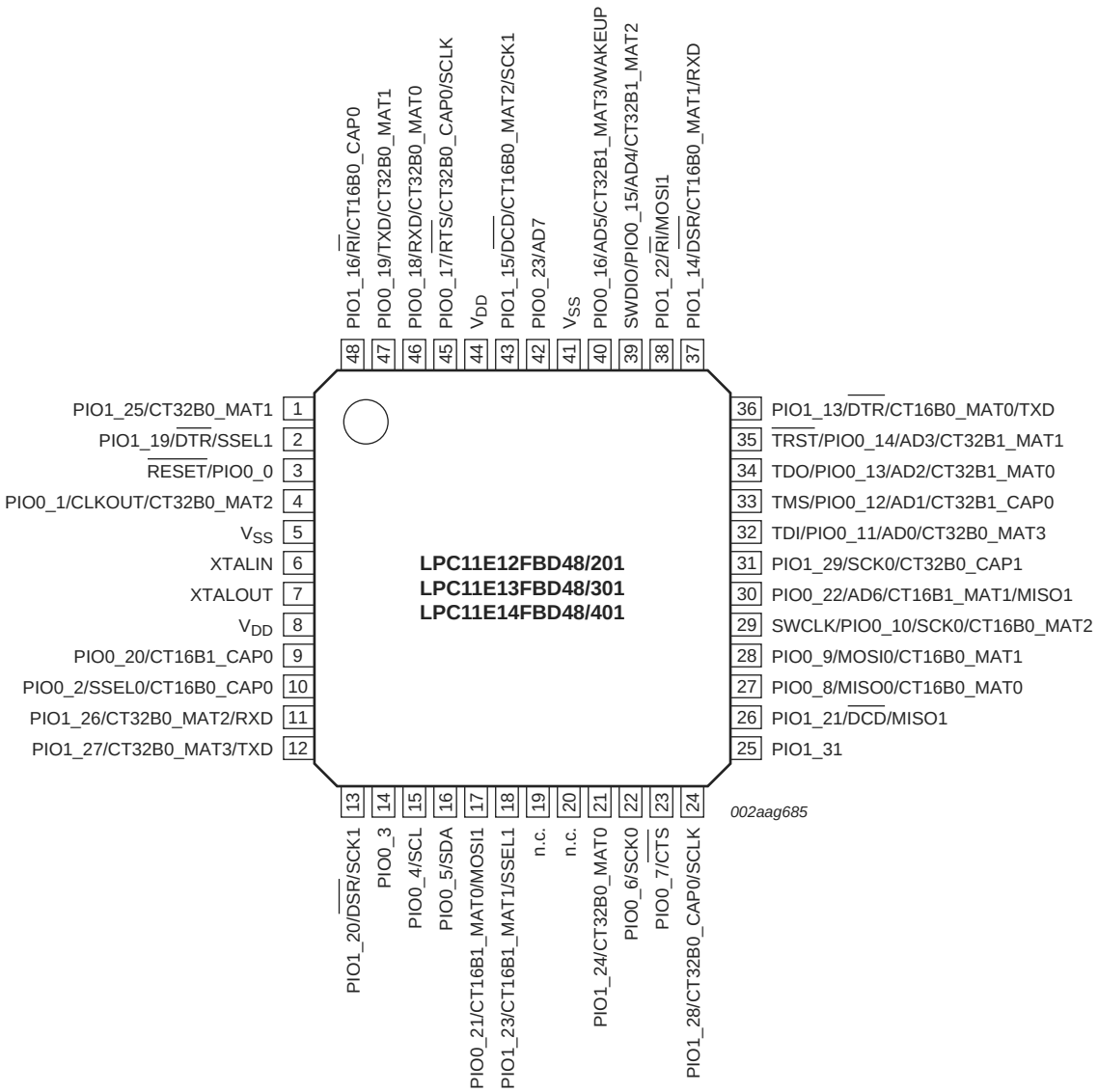


Fig 3. Pin configuration (LQFP48)

Table 3. Pin description

Symbol	HVQFN33	LQFP48	LQFP64		Reset state [1]	Type	Description
PIO1_9	-	-	55	[3]	I; PU	I/O	**PIO1_9 —** General purpose digital input/output pin.
PIO1_10	-	-	12	[3]	I; PU	I/O	**PIO1_10 —** General purpose digital input/output pin.
PIO1_11	-	-	43	[3]	I; PU	I/O	**PIO1_11 —** General purpose digital input/output pin.
PIO1_12	-	-	59	[3]	I; PU	I/O	**PIO1_12 —** General purpose digital input/output pin.
PIO1_13/$\overline{\text{DTR}}$/ CT16B0_MAT0/TXD	-	36	47	[3]	I; PU	I/O	**PIO1_13 —** General purpose digital input/output pin.
					-	O	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for USART.
					-	O	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
					-	O	**TXD —** Transmitter output for USART.
PIO1_14/$\overline{\text{DSR}}$/ CT16B0_MAT1/RXD	-	37	49	[3]	I; PU	I/O	**PIO1_14 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{DSR}}$ —** Data Set Ready input for USART.
					-	O	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.
					-	I	**RXD —** Receiver input for USART.
PIO1_15/$\overline{\text{DCD}}$/ CT16B0_MAT2/SCK1	28	43	57	[3]	I; PU	I/O	**PIO1_15 —** General purpose digital input/output pin.
						I	**$\overline{\text{DCD}}$ —** Data Carrier Detect input for USART.
					-	O	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.
					-	I/O	**SCK1 —** Serial clock for SSP1.
PIO1_16/$\overline{\text{RI}}$/ CT16B0_CAP0	-	48	63	[3]	I; PU	I/O	**PIO1_16 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{RI}}$ —** Ring Indicator input for USART.
					-	I	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
PIO1_17/CT16B0_CAP1/ RXD	-	-	23	[3]	I; PU	I/O	**PIO1_17 —** General purpose digital input/output pin.
					-	I	**CT16B0_CAP1 —** Capture input 1 for 16-bit timer 0.
					-	I	**RXD —** Receiver input for USART.
PIO1_18/CT16B1_CAP1/ TXD	-	-	28	[3]	I; PU	I/O	**PIO1_18 —** General purpose digital input/output pin.
					-	I	**CT16B1_CAP1 —** Capture input 1 for 16-bit timer 1.
					-	O	**TXD —** Transmitter output for USART.
PIO1_19/$\overline{\text{DTR}}$/SSEL1	1	2	3	[3]	I; PU	I/O	**PIO1_19 —** General purpose digital input/output pin.
					-	O	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for USART.
					-	I/O	**SSEL1 —** Slave select for SSP1.
PIO1_20/$\overline{\text{DSR}}$/SCK1	-	13	18	[3]	I; PU	I/O	**PIO1_20 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{DSR}}$ —** Data Set Ready input for USART.
					-	I/O	**SCK1 —** Serial clock for SSP1.
PIO1_21/$\overline{\text{DCD}}$/MISO1	-	26	35	[3]	I; PU	I/O	**PIO1_21 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{DCD}}$ —** Data Carrier Detect input for USART.
					-	I/O	**MISO1 —** Master In Slave Out for SSP1.
PIO1_22/$\overline{\text{RI}}$/MOSI1	-	38	51	[3]	I; PU	I/O	**PIO1_22 —** General purpose digital input/output pin.
					-	I	**$\overline{\text{RI}}$ —** Ring Indicator input for USART.
					-	I/O	**MOSI1 —** Master Out Slave In for SSP1.

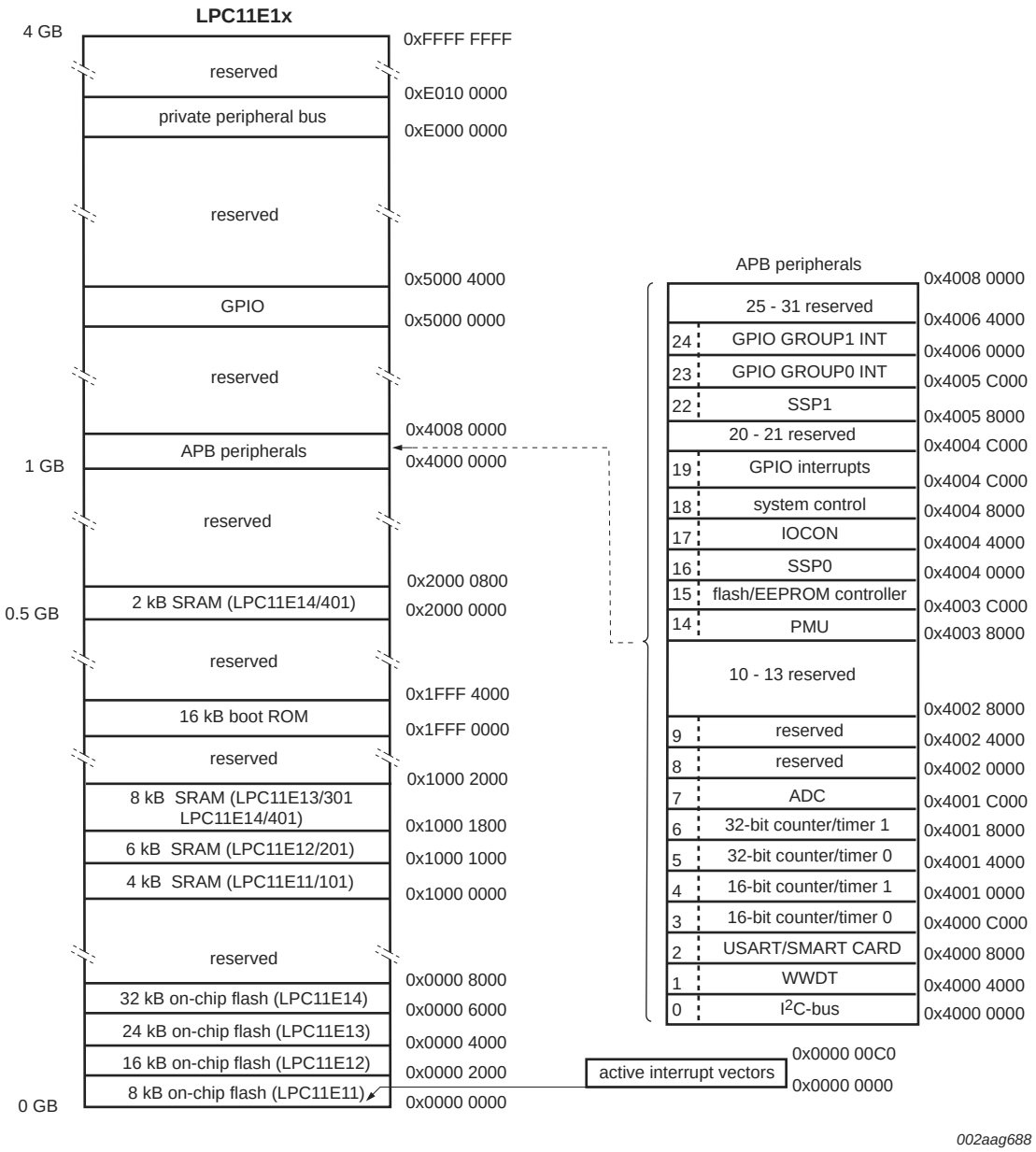


Fig 5. LPC11E1x memory map

7.6 Nested Vectored Interrupt Controller (NVIC)

The Nested Vectored Interrupt Controller (NVIC) is part of the Cortex-M0. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

7.6.1 Features

- Controls system exceptions and peripheral interrupts.
- In the LPC11E1x, the NVIC supports 24 vectored interrupts.

7.8.1 Features

- GPIO pins can be configured as input or output by software.
- All GPIO pins default to inputs with interrupt disabled at reset.
- Pin registers allow pins to be sensed and set individually.
- Up to eight GPIO pins can be selected from all GPIO pins to create an edge- or level-sensitive GPIO interrupt request.
- Any pin or pins in each port can trigger a port interrupt.

7.9 USART

The LPC11E1x contain one USART.

The USART includes full modem control, support for synchronous mode, and a smart card interface. The RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

The USART uses a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

7.9.1 Features

- Maximum USART data bit rate of 3.125 Mbit/s.
- 16 byte receive and transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Fractional divider for baud rate control, auto baud capabilities and FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode.
- Support for modem control.
- Support for synchronous mode.
- Includes smart card interface.

7.10 SSP serial I/O controller

The SSP controllers operate on a SSP, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bit to 16 bit of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.10.1 Features

- Maximum SSP speed of 25 Mbit/s (master) or 4.17 Mbit/s (slave) (in SSP mode)
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses

- Synchronous serial communication
- Master or slave operation
- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame

7.11 I²C-bus serial I/O controller

The LPC11E1x contain one I²C-bus controller.

The I²C-bus is bidirectional for inter-IC control using only two wires: a Serial Clock line (SCL) and a Serial Data line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C-bus is a multi-master bus, and more than one bus master connected to the interface can be controlled the bus.

7.11.1 Features

- The I²C-interface is an I²C-bus compliant interface with open-drain pins. The I²C-bus interface supports Fast-mode Plus with bit rates up to 1 Mbit/s.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.
- The I²C-bus controller supports multiple address recognition and a bus monitor mode.

7.12 10-bit ADC

The LPC11E1x contains one ADC. It is a single 10-bit successive approximation ADC with eight channels.

7.12.1 Features

- 10-bit successive approximation ADC.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 V to V_{DD}.
- 10-bit conversion time $\geq$ 2.44 μs (up to 400 kSamples/s).
- Burst conversion mode for single or multiple inputs.

- Optional conversion on transition of input pin or timer match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.

7.13 General purpose external event counter/timers

The LPC11E1x include two 32-bit counter/timers and two 16-bit counter/timers. The counter/timer is designed to count cycles of the system derived clock. It can optionally generate interrupts or perform other actions at specified timer values, based on four match registers. Each counter/timer also includes one capture input to trap the timer value when an input signal transitions, optionally generating an interrupt.

7.13.1 Features

- A 32-bit/16-bit timer/counter with a programmable 32-bit/16-bit prescaler.
- Counter or timer operation.
- Up to two capture channels per timer, that can take a snapshot of the timer value when an input signal transitions. A capture event can also generate an interrupt.
- Four match registers per timer that allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Up to four external outputs corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.
- The timer and prescaler can be configured to be cleared on a designated capture event. This feature permits easy pulse-width measurement by clearing the timer on the leading edge of an input pulse and capturing the timer value on the trailing edge.

7.14 System tick timer

The ARM Cortex-M0 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a fixed time interval (typically 10 ms).

7.15 Windowed WatchDog Timer (WWDT)

The purpose of the WWDT is to prevent an unresponsive system state. If software fails to update the watchdog within a programmable time window, the watchdog resets the microcontroller

7.15.1 Features

- Internally resets chip if not periodically reloaded during the programmable time-out period.
- Optional windowed operation requires reload to occur between a minimum and maximum time period, both programmable.

- Optional warning interrupt can be generated at a programmable time before watchdog time-out.
- Software enables the WWDT, but a hardware reset or a watchdog reset/interrupt is required to disable the WWDT.
- Incorrect feed sequence causes reset or interrupt, if enabled.
- Flag to indicate watchdog reset.
- Programmable 24-bit timer with internal prescaler.
- Selectable time period from ($T_{cy(WDCLK)} \times 256 \times 4$) to ($T_{cy(WDCLK)} \times 2^{24} \times 4$) in multiples of $T_{cy(WDCLK)} \times 4$.
- The Watchdog Clock (WDCLK) source can be selected from the IRC or the dedicated watchdog oscillator (WDO). The clock source selection provides a wide range of potential timing choices of watchdog operation under different power conditions.

7.16 Clocking and power control

7.16.1 Integrated oscillators

The LPC11E1x include three independent oscillators: the system oscillator, the Internal RC oscillator (IRC), and the watchdog oscillator. Each oscillator can be used for more than one purpose as required in a particular application.

Following reset, the LPC11E1x operates from the internal RC oscillator until software switches to a different clock source. The IRC allows the system to operate without any external crystal and the bootloader code to operate at a known frequency.

See Figure 6 for an overview of the LPC11E1x clock generation.

7.16.5.2 Sleep mode

When Sleep mode is entered, the clock to the core is stopped. Resumption from the Sleep mode does not need any special sequence but re-enabling the clock to the ARM core.

In Sleep mode, execution of instructions is suspended until either a reset or interrupt occurs. Peripheral functions continue operation during Sleep mode and can generate interrupts to cause the processor to resume execution. Sleep mode eliminates dynamic power used by the processor itself, by memory systems and related controllers, and by internal buses.

7.16.5.3 Deep-sleep mode

In Deep-sleep mode, the LPC11E1x is in Sleep-mode and all peripheral clocks and all clock sources are off except for the IRC. The IRC output is disabled unless the IRC is selected as input to the watchdog timer. In addition all analog blocks are shut down and the flash is in stand-by mode. In Deep-sleep mode, the application can keep the watchdog oscillator and the BOD circuit running for self-timed wake-up and BOD protection.

The LPC11E1x can wake up from Deep-sleep mode via reset, selected GPIO pins, or a watchdog timer interrupt.

Deep-sleep mode saves power and allows for short wake-up times.

7.16.5.4 Power-down mode

In Power-down mode, the LPC11E1x is in Sleep-mode and all peripheral clocks and all clock sources are off except for watchdog oscillator if selected. In addition all analog blocks and the flash are shut down. In Power-down mode, the application can keep the BOD circuit running for BOD protection.

The LPC11E1x can wake up from Power-down mode via reset, selected GPIO pins, or a watchdog timer interrupt.

Power-down mode reduces power consumption compared to Deep-sleep mode at the expense of longer wake-up times.

7.16.5.5 Deep power-down mode

In Deep power-down mode, power is shut off to the entire chip except for the WAKEUP pin. The LPC11E1x can wake up from Deep power-down mode via the WAKEUP pin.

The LPC11E1x can be prevented from entering Deep power-down mode by setting a lock bit in the PMU block. Locking out Deep power-down mode enables the application to keep the watchdog timer or the BOD running at all times.

When entering Deep power-down mode, an external pull-up resistor is required on the WAKEUP pin to hold it HIGH. Pull the $\overline{\text{RESET}}$ pin HIGH to prevent it from floating while in Deep power-down mode.

CAUTION

If level three Code Read Protection (CRP3) is selected, no future factory testing can be performed on the device.

In addition to the three CRP levels, sampling of pin PIO0_1 for valid user code can be disabled. For details, see the *LPC11Exx user manual*.

7.16.6.4 APB interface

The APB peripherals are located on one APB bus.

7.16.6.5 AHBLite

The AHBLite connects the CPU bus of the ARM Cortex-M0 to the flash memory, the main static RAM, and the ROM.

7.16.6.6 External interrupt inputs

All GPIO pins can be level or edge sensitive interrupt inputs.

7.17 Emulation and debugging

Debug functions are integrated into the ARM Cortex-M0. Serial wire debug functions are supported in addition to a standard JTAG boundary scan. The ARM Cortex-M0 is configured to support up to four breakpoints and two watch points.

The $\overline{\text{RESET}}$ pin selects between the JTAG boundary scan ($\overline{\text{RESET}}$ = LOW) and the ARM SWD debug ($\overline{\text{RESET}}$ = HIGH). The ARM SWD debug port is disabled while the LPC11E1x is in reset.

To perform boundary scan testing, follow these steps:

1. Erase any user code residing in flash.
2. Power up the part with the $\overline{\text{RESET}}$ pin pulled HIGH externally.
3. Wait for at least 250 μs.
4. Pull the $\overline{\text{RESET}}$ pin LOW externally.
5. Perform boundary scan operations.
6. Once the boundary scan operations are completed, assert the $\overline{\text{TRST}}$ pin to enable the SWD debug mode, and release the $\overline{\text{RESET}}$ pin (pull HIGH).

Remark: The JTAG interface cannot be used for debug purposes.

Table 5. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I²C-bus pins (PIO0_4 and PIO0_5)							
V_{IH}	HIGH-level input voltage			$0.7V_{DD}$	-	-	V
V_{IL}	LOW-level input voltage			-	-	$0.3V_{DD}$	V
V_{hys}	hysteresis voltage			-	$0.05V_{DD}$	-	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I²C-bus pins configured as standard mode pins		3.5	-	-	mA
		2.0 V ≤ V_{DD} ≤ 3.6 V					
		1.8 V ≤ V_{DD} < 2.0 V		3	-	-	
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I²C-bus pins configured as Fast-mode Plus pins		20	-	-	mA
		2.0 V ≤ V_{DD} ≤ 3.6 V					
		1.8 V ≤ V_{DD} < 2.0 V		16	-	-	
I_{LI}	input leakage current	V_I = V_{DD}	[13]	-	2	4	μA
		V_I = 5 V		-	10	22	μA
Oscillator pins							
$V_{i(xtal)}$	crystal input voltage			−0.5	1.8	1.95	V
$V_{o(xtal)}$	crystal output voltage			−0.5	1.8	1.95	V
Pin capacitance							
C_{io}	input/output capacitance	pins configured for analog function		-	-	7.1	pF
		I²C-bus pins (PIO0_4 and PIO0_5)		-	-	2.5	pF
		pins configured as GPIO		-	-	2.8	pF

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] IRC enabled; system oscillator disabled; system PLL disabled.

[3] I_{DD} measurements were performed with all pins configured as GPIO outputs driven LOW and pull-up resistors disabled.

[4] BOD disabled.

[5] All peripherals disabled in the AHBCLKCTRL register. Peripheral clocks to USART, SSP0/1 disabled in the SYSCON block.

[6] Low-current mode PWR_LOW_CURRENT selected when running the set_power routine in the power profiles.

[7] IRC disabled; system oscillator enabled; system PLL enabled.

[8] WAKEUP pin pulled HIGH externally. An external pull-up resistor is required on the $\overline{\text{RESET}}$ pin for the Deep power-down mode.

[9] Including voltage on outputs in 3-state mode.

[10] V_{DD} supply voltage must be present.

[11] 3-state outputs go into 3-state mode in Deep power-down mode.

[12] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[13] To V_{SS}.

Table 6. ADC static characteristics

T_{amb} = −40 °C to +85 °C unless otherwise specified; ADC frequency 4.5 MHz, V_{DD} = 2.5 V to 3.6 V.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	V_{DD}	V
C_{ia}	analog input capacitance			-	-	1	pF
E_D	differential linearity error		[1][2]	-	-	±1	LSB
$E_{L(adj)}$	integral non-linearity		[3]	-	-	±1.5	LSB
E_O	offset error		[4]	-	-	±3.5	LSB
E_G	gain error		[5]	-	-	0.6	%
E_T	absolute error		[6]	-	-	±4	LSB
R_{vsi}	voltage source interface resistance			-	-	40	kΩ
R_i	input resistance		[7][8]	-	-	2.5	MΩ

[1] The ADC is monotonic, there are no missing codes.

[2] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 7.

[3] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 7.

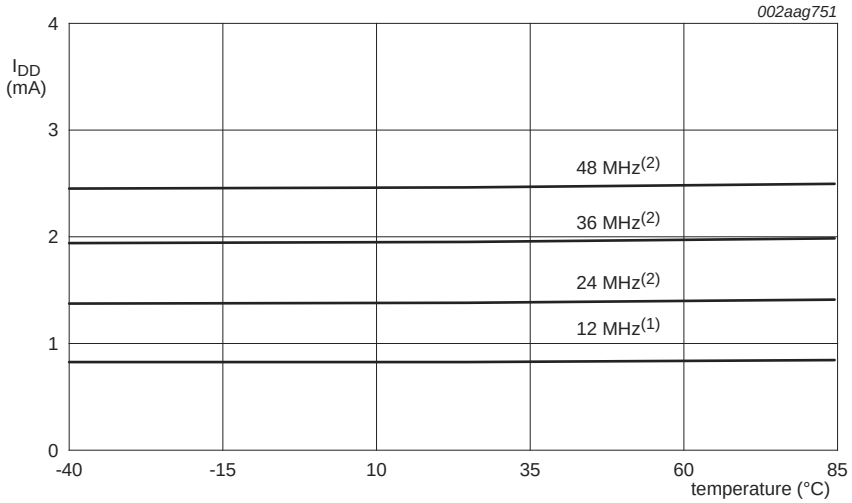
[4] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 7.

[5] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 7.

[6] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 7.

[7] T_{amb} = 25 °C; maximum sampling frequency f_s = 400kSamples/s and analog input capacitance C_{ia} = 1 pF.

[8] Input resistance R_i depends on the sampling frequency fs: $R_i = 1 / (f_s \times C_{ia})$.

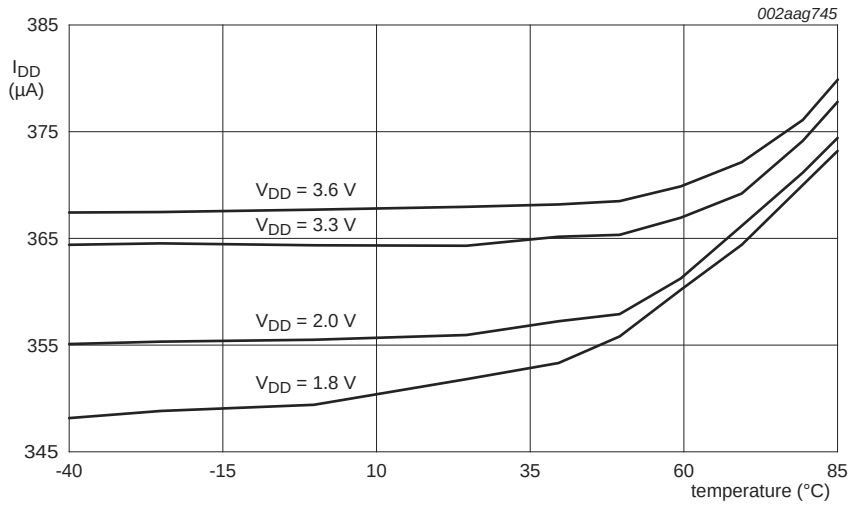


Conditions: V_{DD} = 3.3 V; Sleep mode entered from flash; internal pull-up resistors disabled; BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register; all peripheral clocks disabled; low-current mode.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

Fig 10. Typical supply current versus temperature in Sleep mode



Conditions: BOD disabled; all oscillators and analog blocks turned off in the PDSLEEPCFG register.

Fig 11. Typical supply current versus temperature in Deep-sleep mode

10. Dynamic characteristics

10.1 Flash memory

Table 9. Flash characteristics

T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
N_{endu}	endurance		[1]	10000	100000	-	cycles
t_{ret}	retention time	powered		10	-	-	years
		unpowered		20	-	-	years
t_{er}	erase time	sector or multiple consecutive sectors		95	100	105	ms
t_{prog}	programming time		[2]	0.95	1	1.05	ms

[1] Number of program/erase cycles.

[2] Programming times are given for writing 256 bytes from RAM to the flash. Data must be written to the flash in blocks of 256 bytes.

Table 10. EEPROM characteristics

T_{amb} = −40 °C to +85 °C; V_{DD} = 2.7 V to 3.6 V. Based on JEDEC NVM qualification. Failure rate < 10 ppm for parts as specified below.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
N_{endu}	endurance		100000	1000000	-	cycles
t_{ret}	retention time	powered	100	200	-	years
		unpowered	150	300	-	years
t_{prog}	programming time	64 bytes	-	2.9	-	ms

10.2 External clock

Table 11. Dynamic characteristic: external clock

T_{amb} = −40 °C to +85 °C; V_{DD} over specified ranges.[1]

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Unit
f_{osc}	oscillator frequency		1	-	25	MHz
$T_{cy(clk)}$	clock cycle time		40	-	1000	ns
t_{CHCX}	clock HIGH time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCX}	clock LOW time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCH}	clock rise time		-	-	5	ns
t_{CHCL}	clock fall time		-	-	5	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

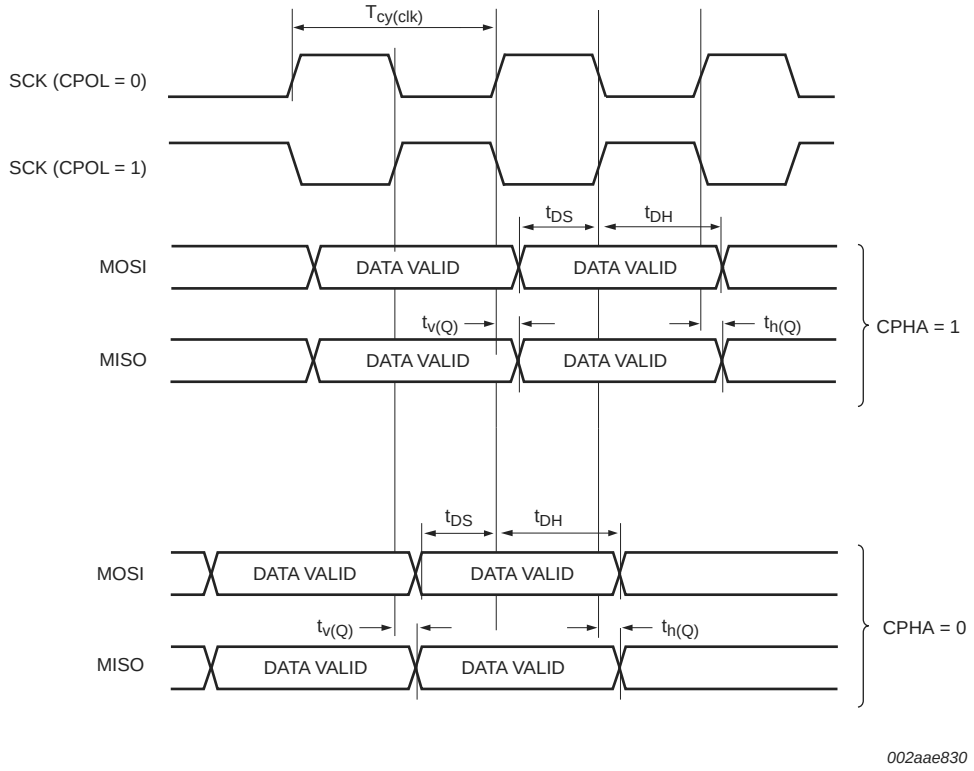


Fig 24. SSP slave timing in SPI mode

11. Application information

11.1 XTAL input

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with C_i = 100 pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor $C_i/(C_i + C_g)$. In slave mode, a minimum of 200 mV(RMS) is needed.

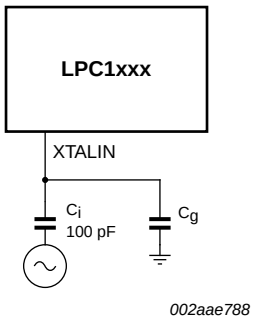


Fig 25. Slave mode operation of the on-chip oscillator

In slave mode, couple the input clock signal with a capacitor of 100 pF (Figure 25), with an amplitude between 200 mV(RMS) and 1000 mV(RMS). This signal corresponds to a square wave signal with a signal swing of between 280 mV and 1.4 V. The XTALOUT pin in this configuration can be left unconnected.

External components and models used in oscillation mode are shown in Figure 26 and in Table 17 and Table 18. Since the feedback resistance is integrated on chip, only a crystal and the capacitances C_{X1} and C_{X2} need to be connected externally in case of fundamental mode oscillation (L, C_L and R_S represent the fundamental frequency). Capacitance C_P in Figure 26 represents the parallel package capacitance and must not be larger than 7 pF. Parameters F_{OSC}, C_L, R_S and C_P are supplied by the crystal manufacturer.

- Connect the external components to the ground plain.
- To keep parasitics and the noise coupled in via the PCB as small as possible, keep loops as small as possible.
- Choose smaller values of C_{x1} and C_{x2} if parasitics of the PCB layout increase.

11.3 Standard I/O pad configuration

Figure 27 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Analog input

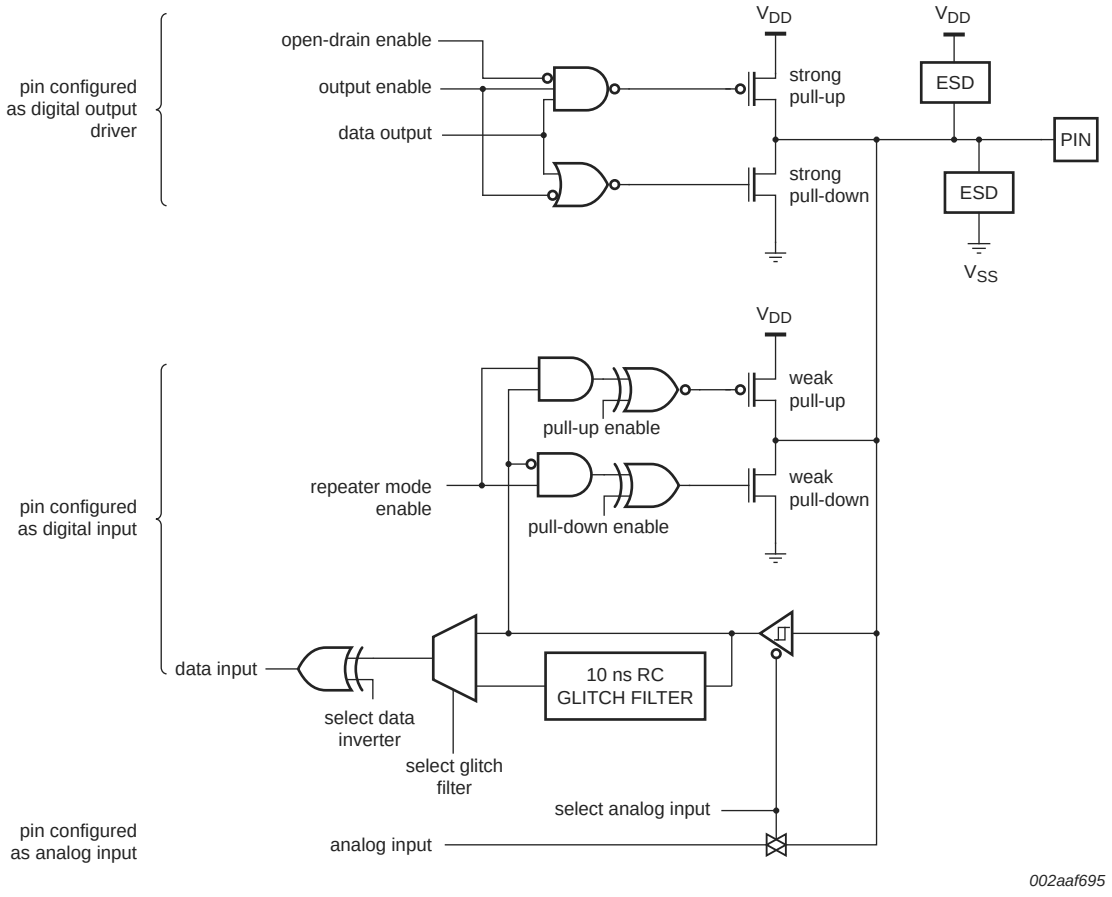
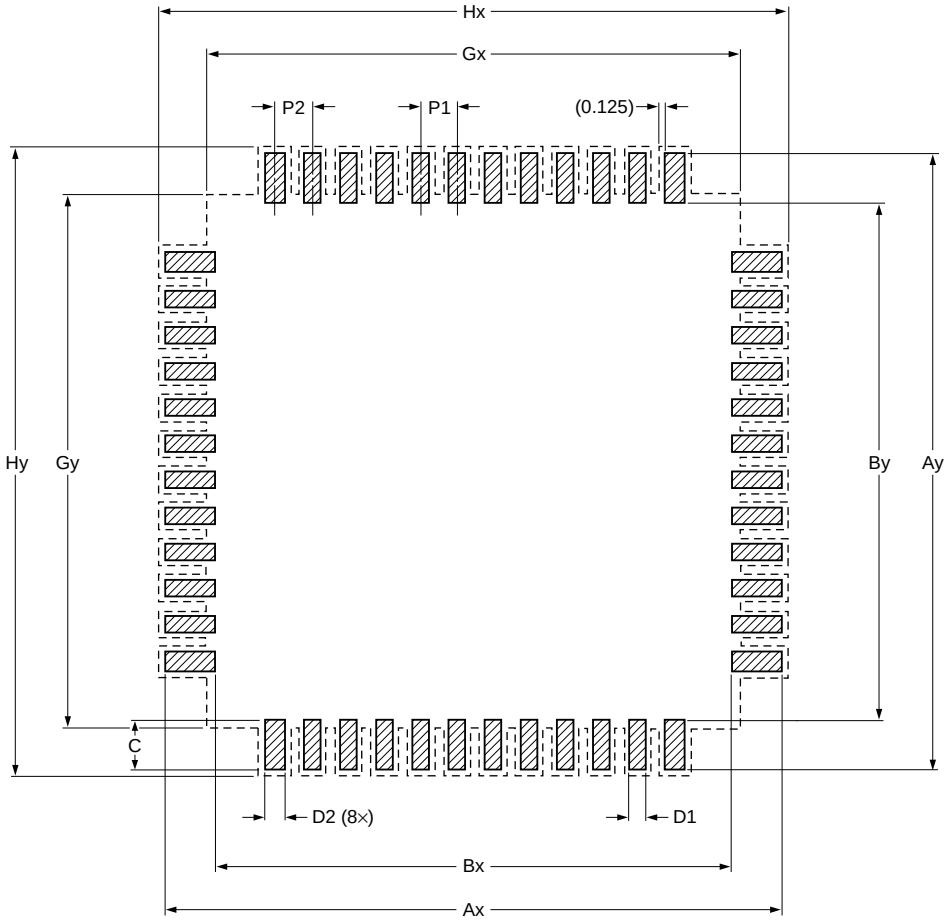


Fig 27. Standard I/O pad configuration

Footprint information for reflow soldering of LQFP48 package **SOT313-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	10.350	10.350	7.350	7.350	1.500	0.280	0.500	7.500	7.500	10.650	10.650

sot313-2_fr

Fig 34. Reflow soldering for the LQFP48 package

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